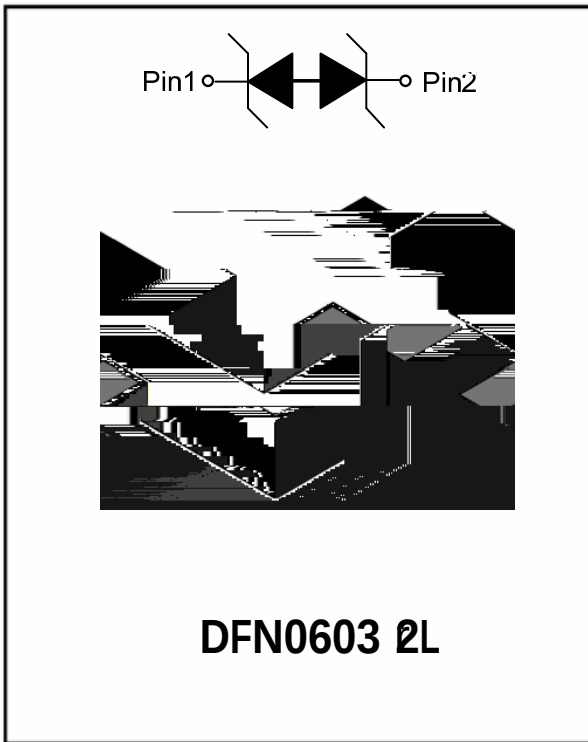


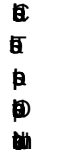
1- L pBiLED



Fa



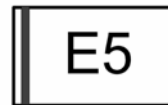
Ap



MC

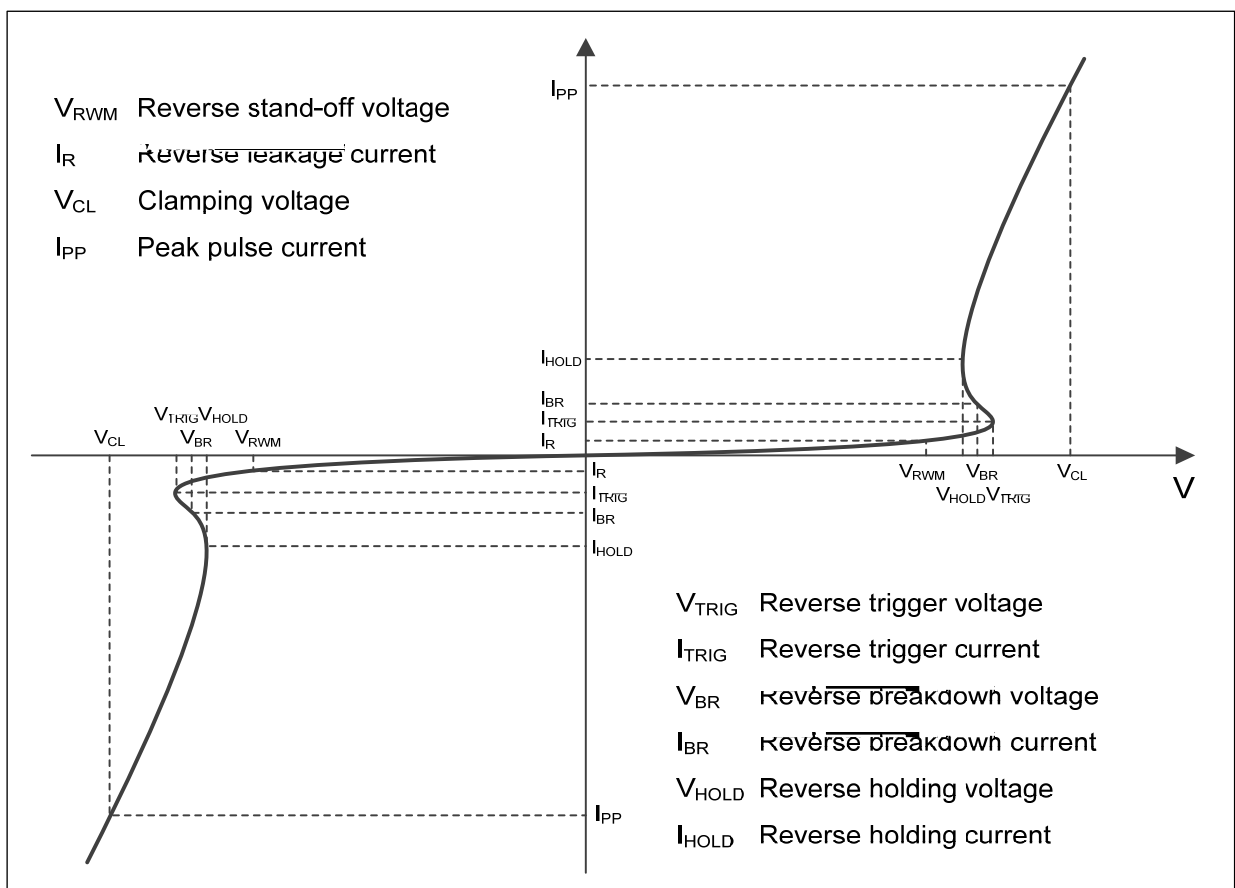


Pin1



Pin2

VD





ED50 L BA

VA

ARMER	MO L	Rating	W
P_{p}	P_{p}	2	W
I_{p}	I_{p}	6	A
	V_{B}	8	K
		8	K
T_{J}	T_{J}	2	°C
T_{B}	T_{B}	8	°C
T	T	8	°C

VECh

T a s

ARMER	W			M	P	M
V	V	V			8	
I	R	$A V$	$W B$		0	
	V_{B}	V	I_{B}	5		7
V	B	V	I_{B}	5		7
¹⁾	V_{C}	V	I_{P}		7	
¹⁾	R_{B}				0	
²⁾	V_{C}	V	V_{B}		8	
³⁾	V_{C}	V	I_{P}		6	7
		V	I_{P}		8	8
		V	I_{P}		8	9
C_{J}	C_{J}	$P V$	R_{B}		5	5
		$P V$	R_{B}		8	5

08 t p

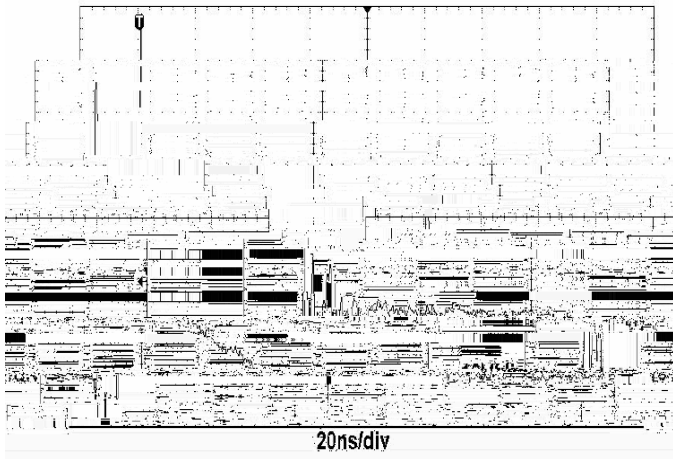
8 8



四

Contact discharge: Li^+ & Sis^{OC} Card EC61000 r

ESD clamping
(+8kV contact discharge per IEC61000 # 2)



ESD clamping
(8kV contact discharge per IEC61000 # 2)



TLP Measurement

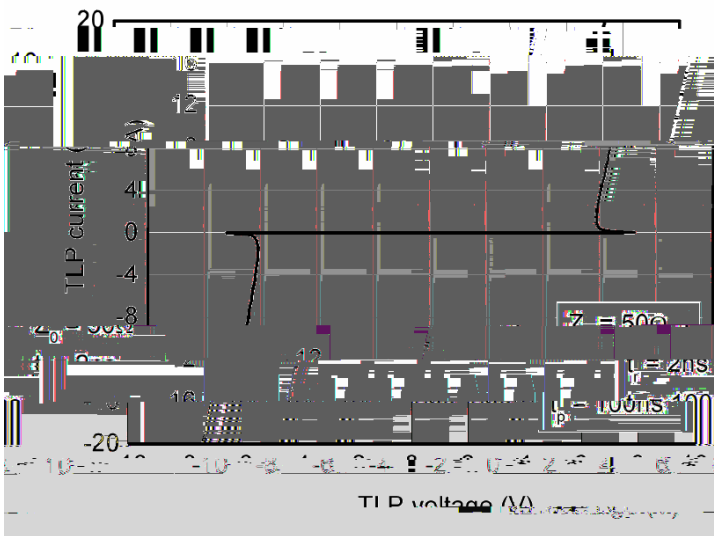
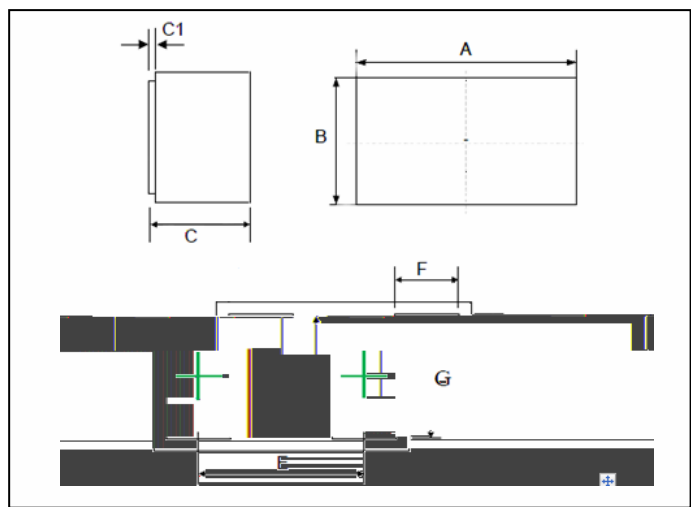




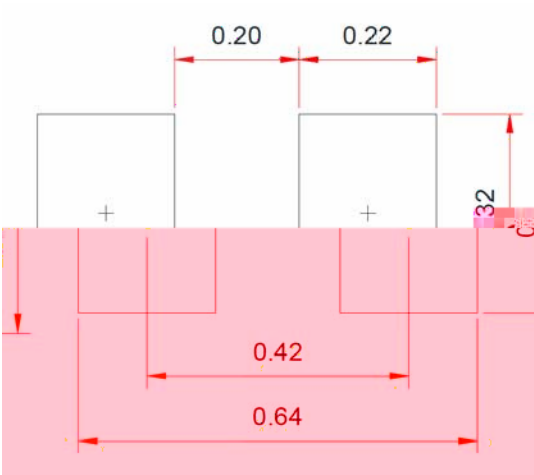
Figure 1



6 \ P E R O	P L Q	P P	0 D
\$			
%			
&			
&			
(			
)			
*			

P P

Figure 2



Notes:
This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met



ED50

L

BA

Din